

**AMENDMENTS TO THE DRAWINGS**

Please replace the drawing sheets on file that contain Figures 1, 13, 14 and 15  
with the amended drawing sheets submitted herewith.

**REMARKS**

Claims 1-12 are pending in the application. Claims 1, 2, 4-9 and 11 have been withdrawn from consideration. The drawings and title have been objected to. Claims 3, 10 and 12 have been rejected under 35 U.S.C. § 103(a) over Frezza (U.S. Patent No. 6,909,166) in view of Harper (Electronic Packaging and Interconnection handbook, 1991, McGraw-Hill, Inc., New York, pp. 618). Claims 3 and 12 have been amended hereby. Reconsideration of the present application in light of the above amendments and below remarks is respectfully requested.

In paragraph 4 of the Office Action, the drawings have been objected to. Specifically, Figures 13-15 have been objected to as not being labeled as prior art. Applicant submits herewith redline and replacement sheets containing amendments to these figures to label them as prior art. The drawings have further been objected to as reference character 21 was incorrectly used to designate the through hole. Figure 1 has been amended to remove the incorrect designation of the through hole as reference character 21. This reference character is properly used in at least Figure 3a to indicate the circuit board. Applicants have submitted herewith redlined and replacement sheets of these drawings in order to correct these errors. No new matter is entered by these corrections. Withdrawal of the objections to the drawings is therefore respectfully requested.

In paragraph 7 of the Office Action, the title of the invention was objected to as not being descriptive. Applicant has amended the title to further describe the nature of the invention. Withdrawal of the objection to the title is therefore respectfully requested.

In paragraphs 8 and 9 of the Office Action, claims 3, 10 and 12 have been rejected under § 103 over Frezza in view of Harper. Applicant respectfully traverses this

rejection. Each of independent claims 3 and 4 require "the plurality of leads do not extend beyond the side surfaces of the molded resin." Neither Frezza or Harper teach or suggest this limitation of the present invention. As illustrated in at least Figures 2, 3A-3B and 9 of the present application, no portion of the lead (7, 10) extends beyond the peripheral surface of the molded resin (13).

In contrast to the present invention, all of the leads in Frezza extend beyond its molded resin as illustrated in at least Figures 7, 8, 9, 12 and 13. There is no suggestion or motivation to modify the Frezza reference to manufacture the semiconductor device with the leads that do not extend beyond the edge of the molded resin as is explicitly recited in independent claims 1 and 4. Harper does not cure this deficiency of Frezza.

Withdrawal of the rejection of independent claims 3 and 4 and dependent claim 10 on the basis of the combination of Frezza and Harper is therefore respectfully requested.

As each of the claims of the present application is currently in condition for allowance such action is earnestly solicited.

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Respectfully submitted,

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REDLINE SHEET

FIG.1

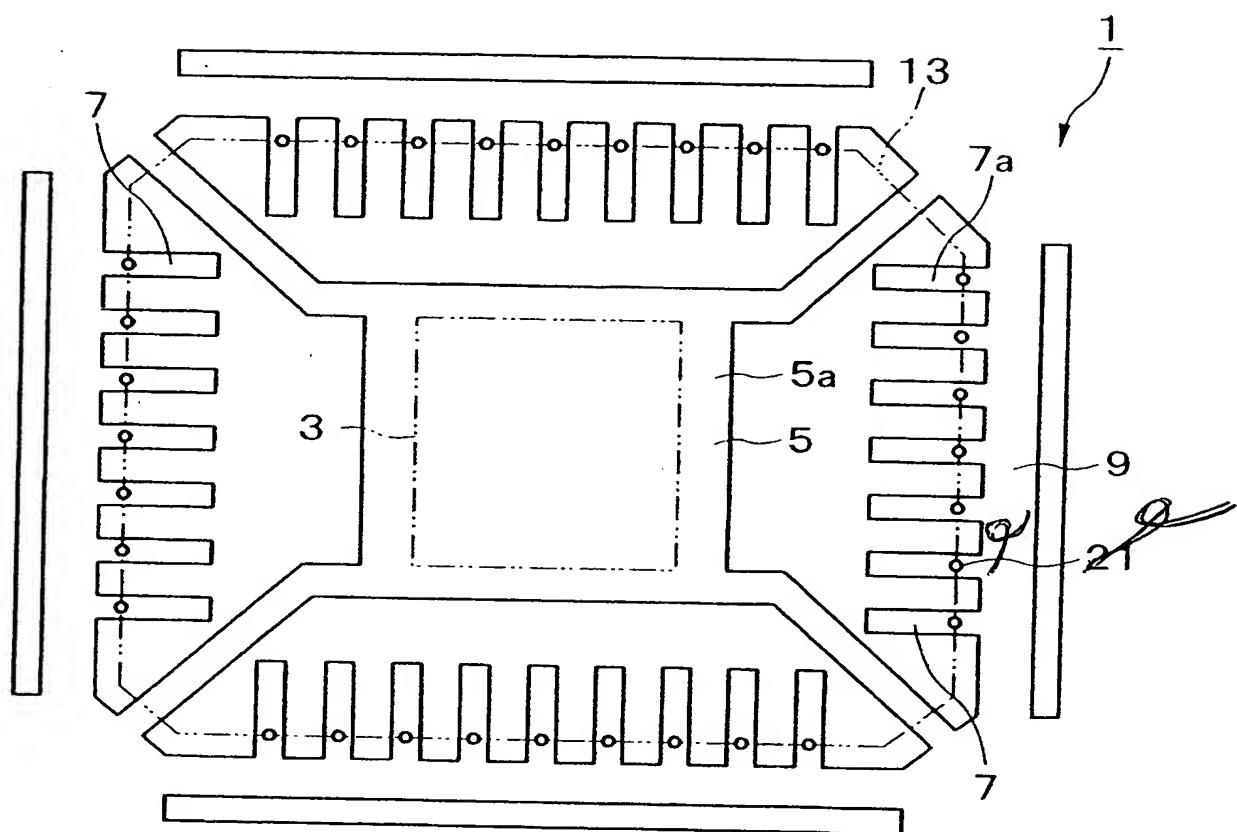


FIG.2

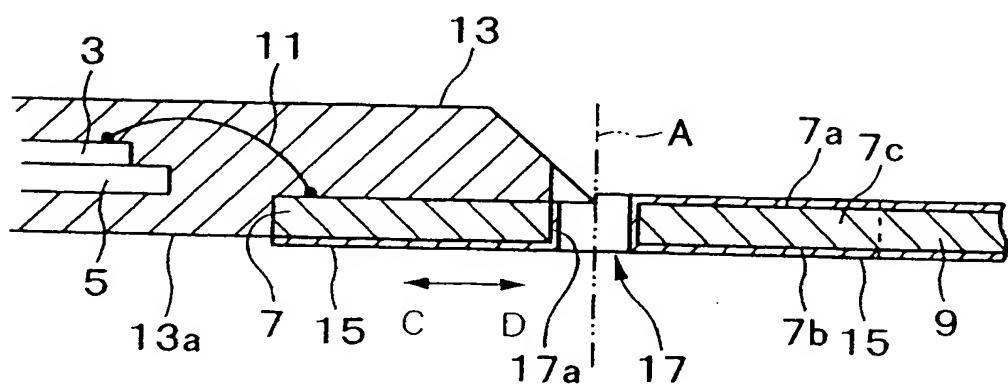


FIG.12

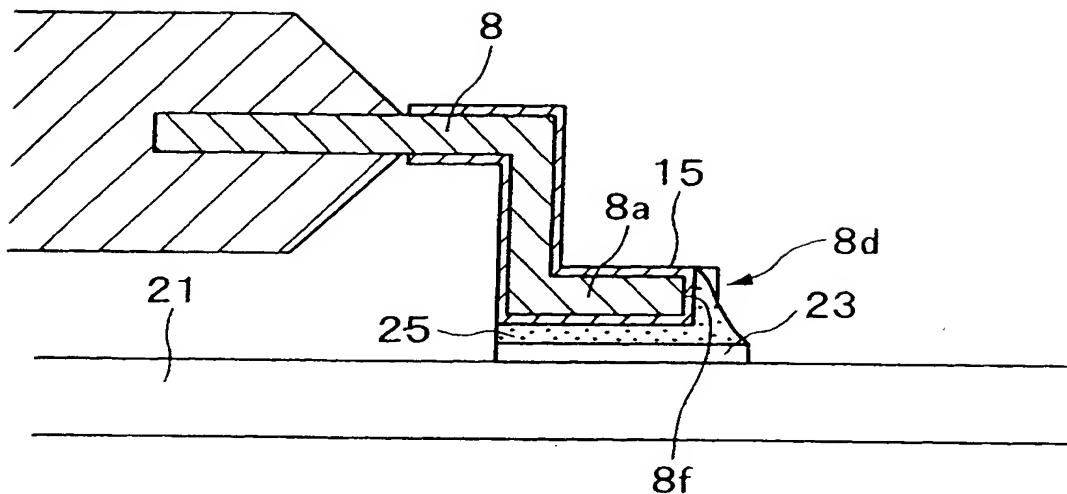
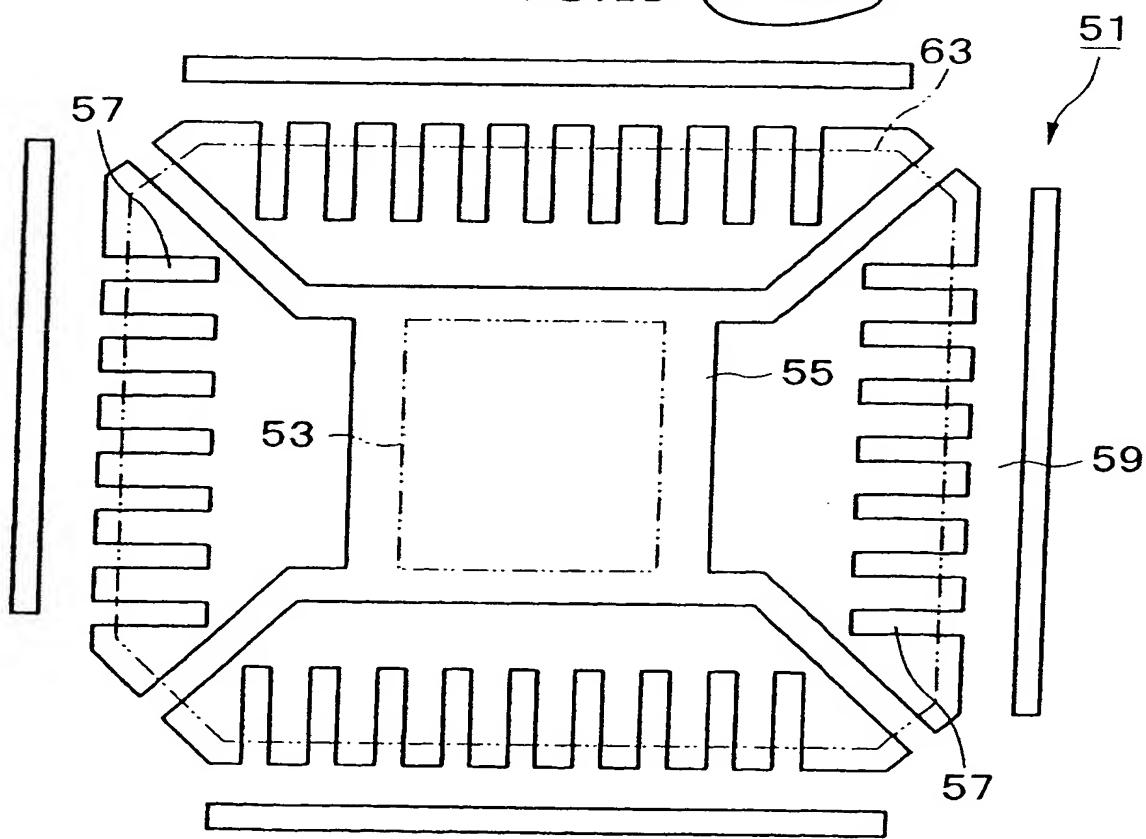


FIG.13 *PRIOR ART*



REDLINE SHEET

FIG.14  
PRIOR ART

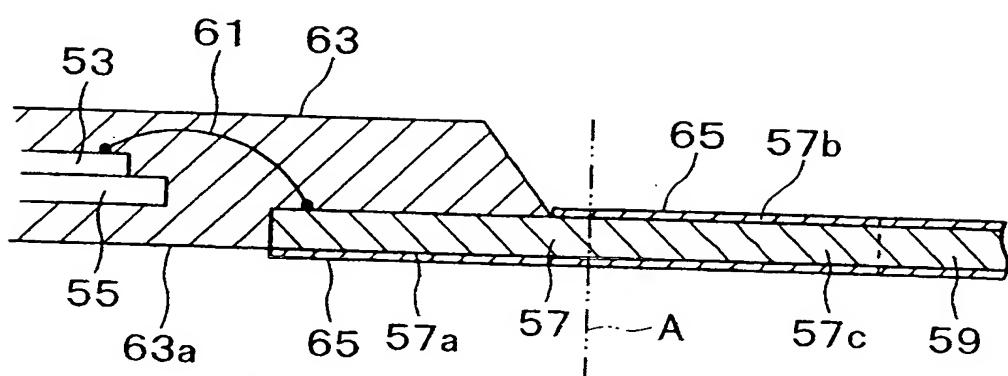


FIG.15  
PRIOR ART

